

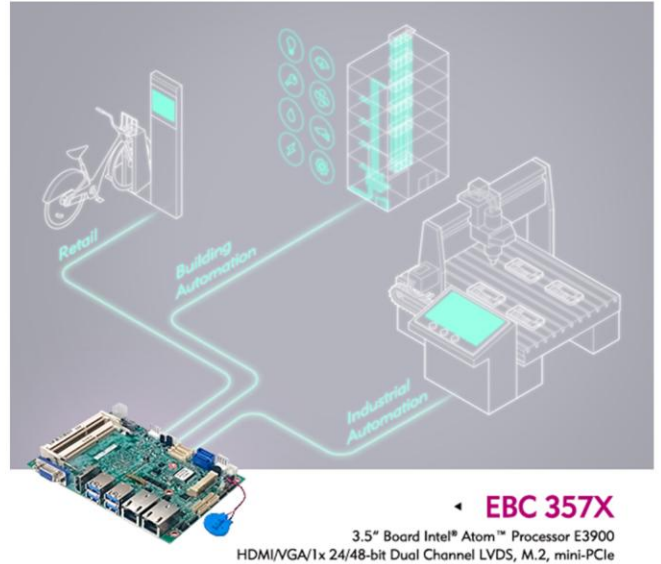


Portwell

MAR 14, 2017

PORTWELL RELEASES A COM EXPRESS® BASIC MODULE DESIGNED WITH 7th GEN INTEL® CORE™ MOBILE PROCESSORS

Portwell today announces the release of the PCOM-B643VG, a COM Express® Type 6 Basic Module (125mm x 95mm) based on the 7th Generation Intel® Core™ mobile processor (codenamed Kaby Lake-H) and Intel® QM175 and CM238 express chipset. [-read more-](#)



NEXCOM

MAR 10, 2017

EBC 357X Series of 3.5" Boards Elevates Processing Power in Human-Machine Interfaces

NEXCOM's EBC 357X series of 3.5" boards improves processing power and enhances display performance in a reliable and power efficient compact design. [-read more-](#)



AAEON®
an ASUS assoc. co.

MAR 10, 2017

UP-GWS01 - TINY GATEWAY SYSTEM WITH UP BOARD

The AAEON UP-GWS01 features a credit-card-sized single board computer designed around the quad-core Intel® Atom™ x5-Z8350 Processor SoC with full support for Intel® RealSense™ technology. Wide-ranging I/O supporting Wi-Fi, Bluetooth, 3G, and touch displays enable a breakthrough degree of expandable functionality to offer a complete compute eco-system. [-read more-](#)



DFI
www.dfi.com

MAR 02, 2017

DFI's New Gen Intel Core Fanless and Small Industrial Computer

As more and more balance is required among high performance, small size, and ability to be fanless in the embedded markets, DFI is glad to introduce to you a brand-new option: EC70A-SU/EC70B-SU industrial box PC powered by 6th Generation Intel® Core™ i7/i5/i3 processor (code name: Skylake). [-read more-](#)